



POWER PC™ 7410E Multi-Chip Package Construction  
WED3C7410E16MC-XBHX  
Quality and Reliability Report

## POWER PC™ 7410E MULTI-CHIP PACKAGE CONSTRUCTION

### HIGH RELIABILITY FLIP CHIP ATTACH

- C4 Assembly on PowerPC™ Processors & SSRAM die
- Moisture sensitivity level is to JEDEC Level 3
- Die Thickness
- Processor - 0.019 Inches
- SSRAM - 0.019 Inches

### INTERPOSER MATERIAL

- Multilayer Ceramic, Al<sub>2</sub>O<sub>3</sub>
- 21 X 25 mm CBGA

### BALLS

- Solder: 63Sn/37Pb or 10Sn/90Pb
- Diameter = 0.835mm (0.032 ) Typical
- 255 Balls in 16 x 16 array (minus one for optical placement), 21mm x 21mm array.
- 1.27 mm pitch

### TEST

- Burn-In - 100%, 48 hours at 125°C
- Final Electrical Test - 100% at maximum and minimum ambient temperatures

#### Temperature Ranges Available:

- 55°C to +125°C
- 40°C to +85°C
- 0°C to +70°C

### SHIPPING

- Shipped in JEDEC standard trays and anti-static shielded bags

## QUALIFICATION INFORMATION

Qual for 255 CBGA Product					
Qual Test	# of Pieces	Duration	Reference Standards	Temp. Range	Results
Preconditioning	All Test Samples		EIA/JESD22 Method A113		Pass
7410 Bias Life Test	15 pcs	1000 hrs.	EIA/JESD22 Method A108	125°C	Pass
Temperature Cycle	15 pcs	1000 cycles	EIA/JESD22 Method A104 Condition C	-65°C to +150°C	Pass
85/85 Bias	15 pcs	1000 hrs.	EIA/JESD22 Method 101		Pass

Per Reliability Report  
200A0004-18

\*PowerPC™ is a trademark of International Business Machines Corporation